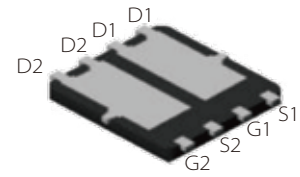


FEATURES

- | Surface-mounted package
- | Advanced trench cell design



PDFN3.3x3.3-8L

APPLICATION

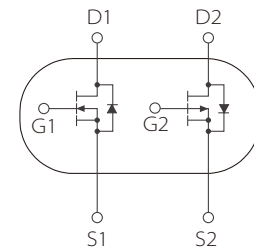
- | MB and NB
- | Motor drivers
- | Half – bridge Drivers



Marking

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003



Schematic Symbol

ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
N-channel				
Drain-Source Voltage	V_{DS}	$T_c=25^\circ\text{C}$	60	V
Gate-Source Voltage	V_{GS}	$T_c=25^\circ\text{C}$	± 20	V
Drain Current	I_D^*	$T_c=25^\circ\text{C}, V_{GS}=10\text{V}$	15.7	A
		$T_c=100^\circ\text{C}, V_{GS}=10\text{V}$	9.9	A
Pulsed Drain Current	I_{DM}^{****}	$T_c=25^\circ\text{C}, V_{GS}=10\text{V}$	34	A
Single Pulsed Avalanche Energy	E_{AS}^*	$V_{DD}=50\text{V}, L=1\text{mH}$	32	mJ
P-channel				
Drain-Source Voltage	V_{DS}	$T_c=25^\circ\text{C}$	-60	V
Gate-Source Voltage	V_{GS}	$T_c=25^\circ\text{C}$	± 20	V
Drain Current	I_D^*	$T_c=25^\circ\text{C}, V_{GS}=-10\text{V}$	-12.2	A
		$T_c=100^\circ\text{C}, V_{GS}=-10\text{V}$	-7.8	A
Pulsed Drain Current	I_{DM}^{****}	$T_c=25^\circ\text{C}, V_{GS}=-10\text{V}$	-34	A
Single Pulsed Avalanche Energy	E_{AS}^*	$V_{DD}=-50\text{V}, L=1\text{mH}$	60.5	mJ
Total Power Dissipation	P_{tot}	$T_c=25^\circ\text{C}$	20.8	W
Junction and Storage Temperature Range	$T_{J,STG}$		-55 to 150	$^\circ\text{C}$
Thermal Resistance- Junction to Ambient	$R_{\theta JA}^*$		56.6	$^\circ\text{C}/\text{W}$
Thermal Resistance- Junction to Case	$R_{\theta JC}^*$		6	$^\circ\text{C}/\text{W}$

Notes: * Surface Mounted on 1 in² pad area, $t \leq 10$ sec
 ** Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
 *** limited by bonding wire

ELECTRICAL CHARACTERISTICS(T_a = 25°C)

N-Channel

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_{DS}=250\mu A$	60			V
Zero Gate Voltage Source Current	I_{DSS}	$V_{DS}=48V, V_{GS}=0V$			1	μA
Gate Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1		2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}^a$	$V_{GS}=10V, I_D=10A$		32	40	m Ω
		$V_{GS}=4.5V, I_D=5A$		38	50	
Diode Characteristics						
Diode Forward Voltage	V_{SD}^a	$V_{GS}=0V, I_{SD}=10A$			1.3	V
Reverse Recovery Time	t_{rr}	$I_{SD}=10A, di_{SD}/dt=100A/\mu s$		10		nS
Reverse Recovery Charge	Q_{rr}			7.8		nC
Dynamic Characteristics^b						
Input Capacitance	C_{iss}	$V_{DS}=30V, V_{GS}=0V$ Frequency = 1 MHz		1061		pF
Output Capacitance	C_{oss}			42		
Reverse Transfer Capacitance	C_{rss}			38		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=30V, R_L=3\Omega$ $V_{GEN}=10V, R_G=3.9\Omega, I_D=10A$		5.8		nS
Turn-On Rise Time	t_r			11		
Turn-Off Delay Time	$t_{d(off)}$			16		
Turn-Off Fall Time	t_f			3.6		
Gate Charge Characteristics^b						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=30V, I_{DS}=10A$		19		nC
Gate Source Charge	Q_{gs}			5		
Gate Drain Charge	Q_{gd}			2.6		

P-Channel

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_{DS}=-250\mu A$	-60			V
Zero Gate Voltage Source Current	I_{DSS}	$V_{DS}=-48V, V_{GS}=0V$			-1	μA
Gate Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-1		-2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}^a$	$V_{GS}=-10V, I_D=-8A$		53	66	m Ω
		$V_{GS}=-4.5V, I_D=-4A$		65	85	
Diode Characteristics						
Diode Forward Voltage	V_{SD}^a	$V_{GS}=0V, I_{SD}=-8A$			-1.3	V
Reverse Recovery Time	t_{rr}	$I_{SD} = -8A, di_{SD}/dt = 100 A/\mu s$		14		nS
Reverse Recovery Charge	Q_{rr}			11		nC
Dynamic Characteristics^b						
Input Capacitance	C_{iss}	$V_{DS}=-30V, V_{GS}=0V$ Frequency = 1 MHz		1428		pF
Output Capacitance	C_{oss}			63		
Reverse Transfer Capacitance	C_{rss}			53		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=-30V, R_L=3.75\Omega$ $V_{GEN}=-10V, R_G=3.9\Omega, I_D = -8A$		5		nS
Turn-On Rise Time	t_r			17		
Turn-Off Delay Time	$t_{d(off)}$			97		
Turn-Off Fall Time	t_f			42		
Gate Charge Characteristics^b						
Total Gate Charge	Q_g	$V_{GS}=-10V, V_{DS}=-30V, I_{DS}=-8A$		24		nC
Gate Source Charge	Q_{gs}			6		
Gate Drain Charge	Q_{gd}			2.8		

Notes: a : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
 b : Guaranteed by design, not subject to production testing

PARAMETER CHARACTERISTIC CURVE

N-Channel

Figure1: Power Capability

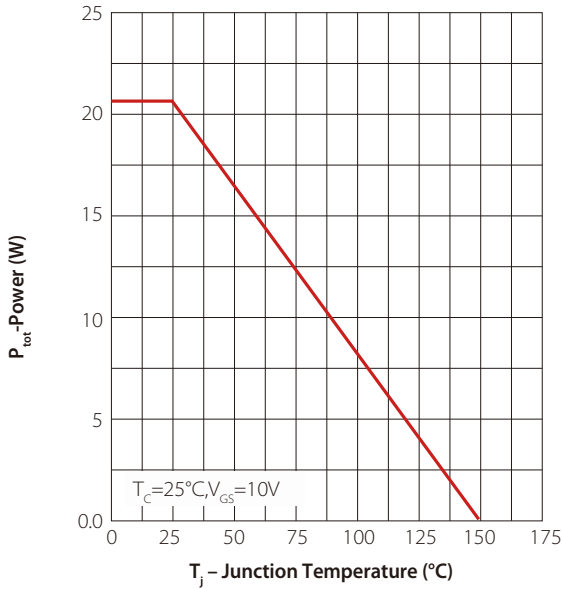


Figure2: Current Capability

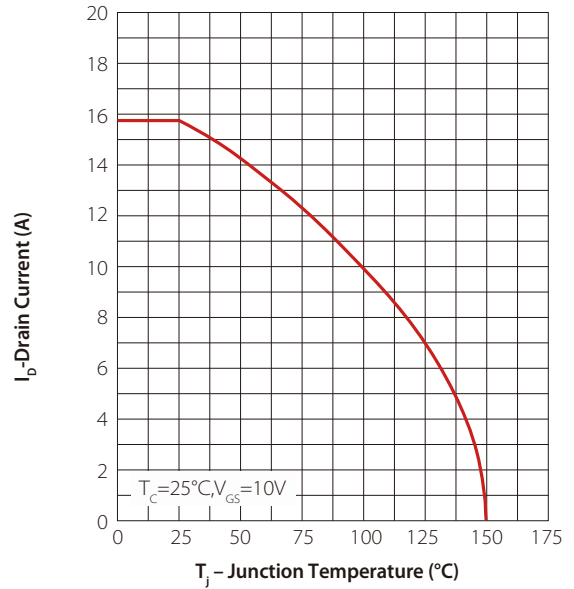


Figure3: Safe Operation Area

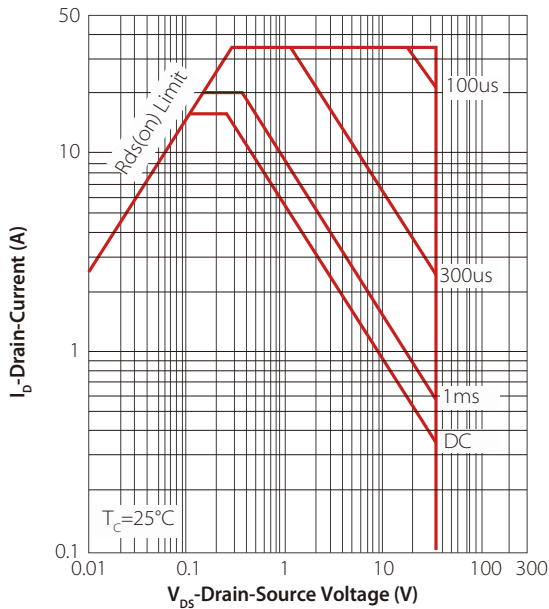


Figure 4: Transient Thermal Impedance

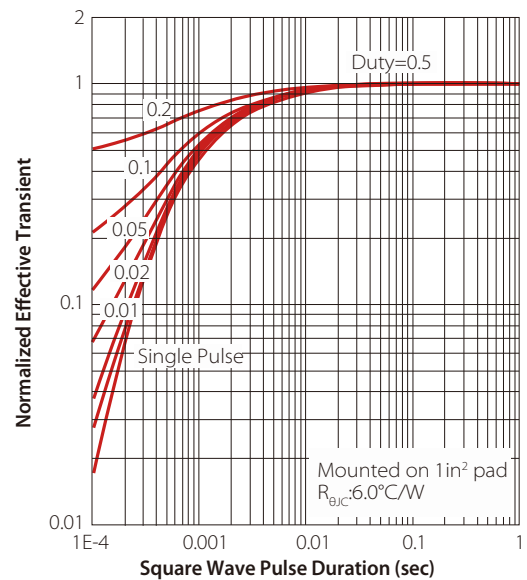


Figure 5: Output Characteristics

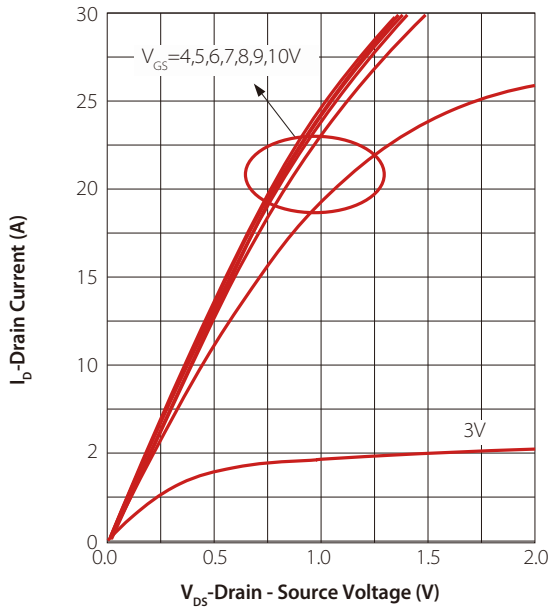


Figure 6: On Resistance

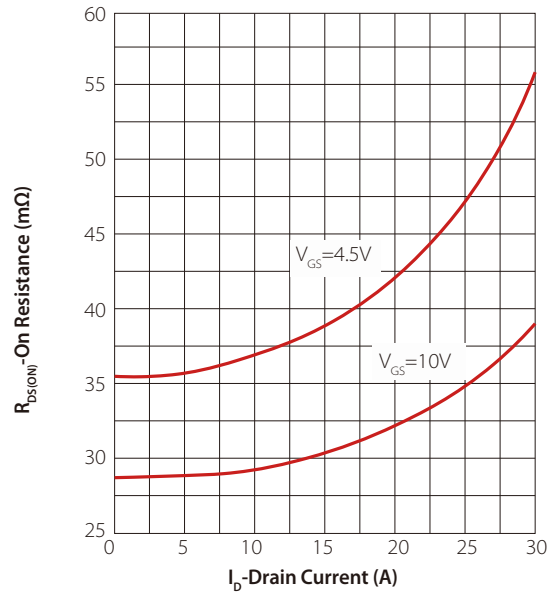


Figure 7: Transfer Characteristics

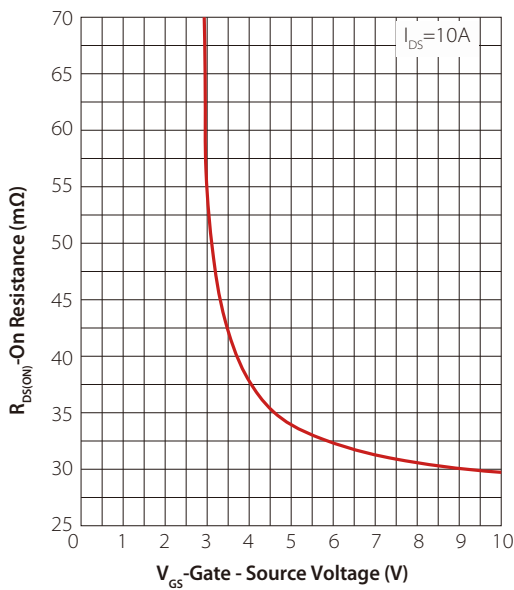


Figure 8: Normalized Threshold Voltage

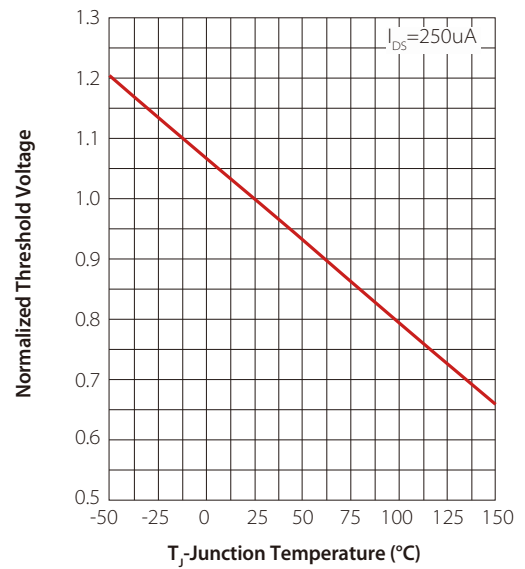


Figure 9: Normalized On Resistance

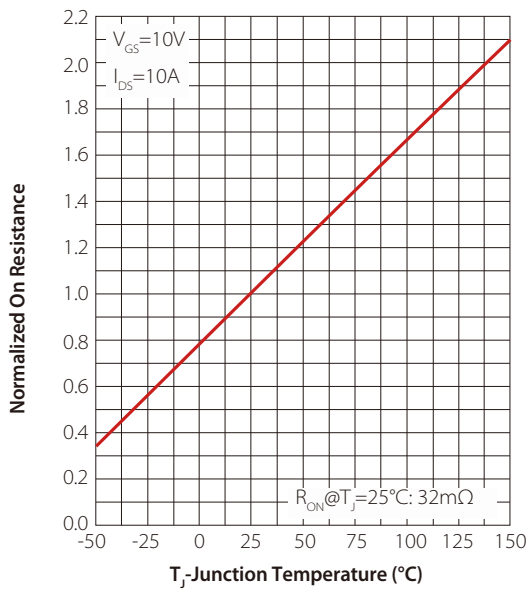


Figure 10: Diode Forward Current

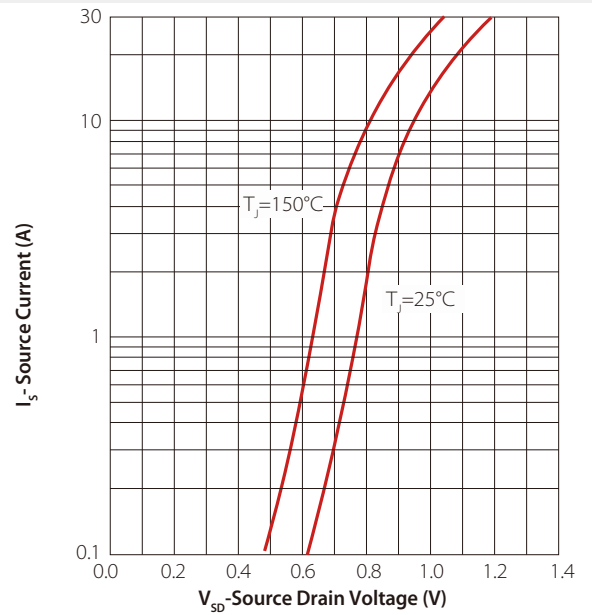


Figure 11: Capacitance

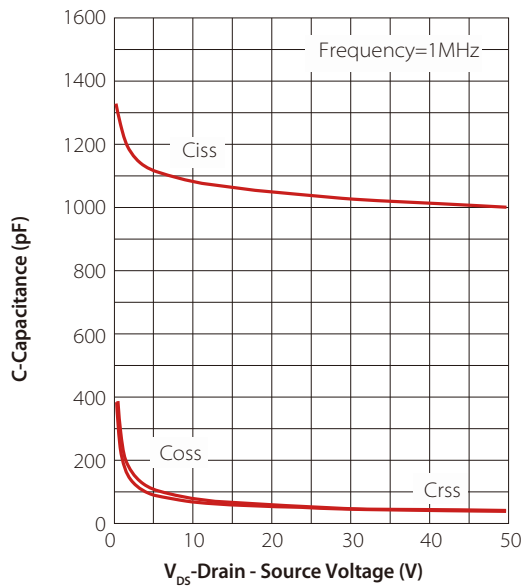
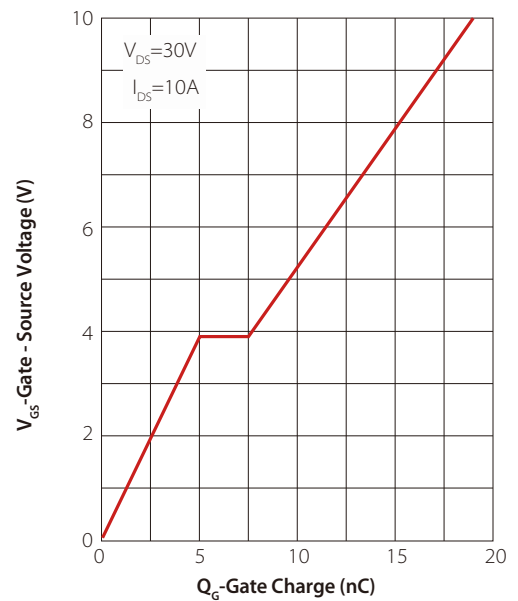


Figure 12: Gate Charge



P-Channel

Figure13: Power Capability

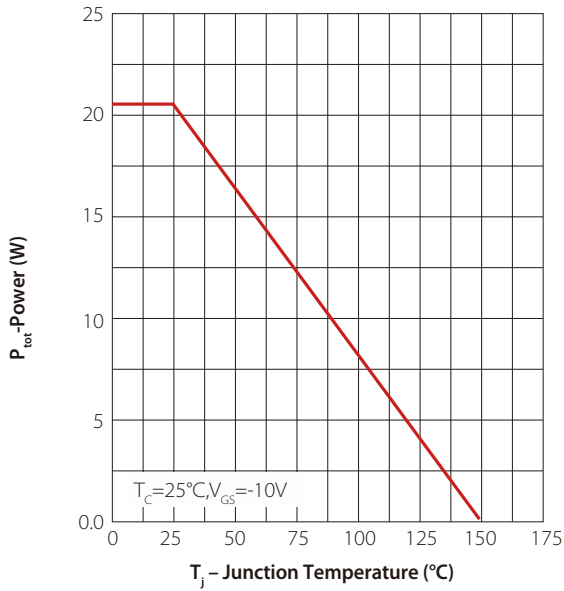


Figure14: Current Capability

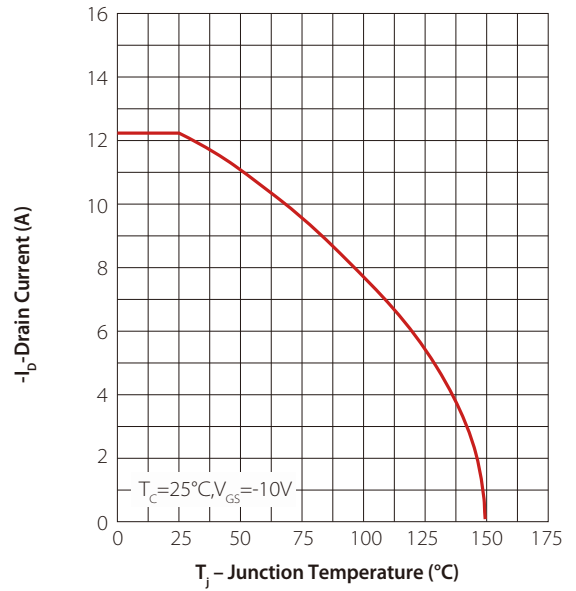


Figure15: Safe Operation Area

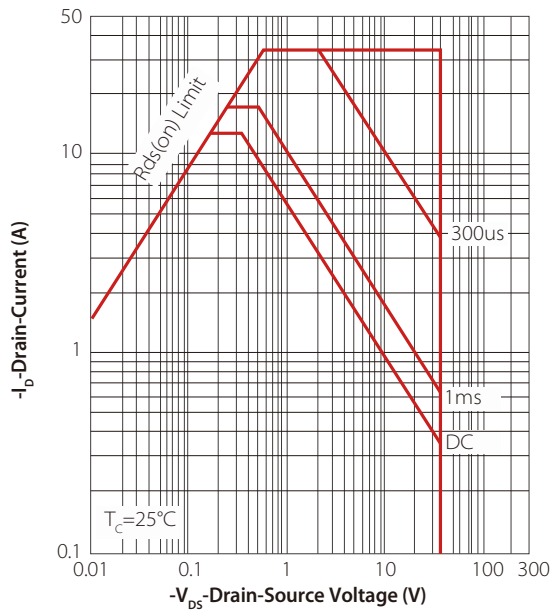


Figure 16: Transient Thermal Impedance

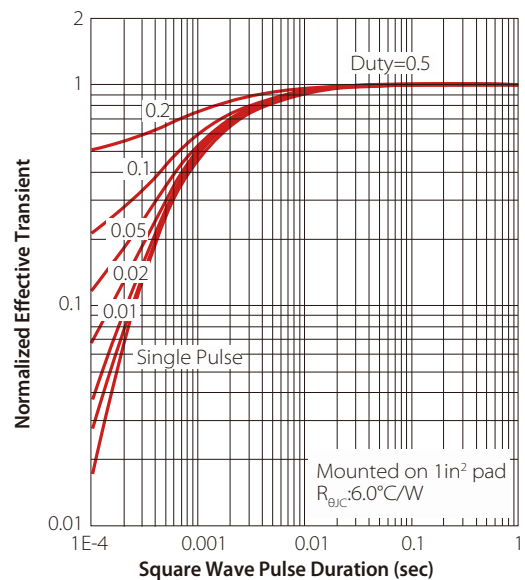


Figure 17: Output Characteristics

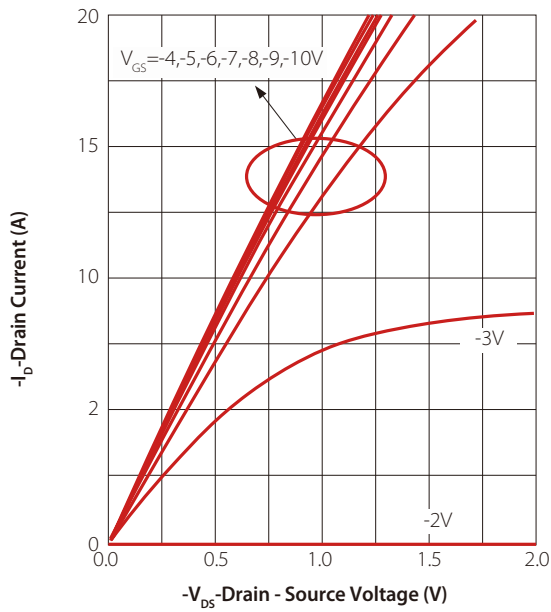


Figure 18: Drain-Source On Resistance

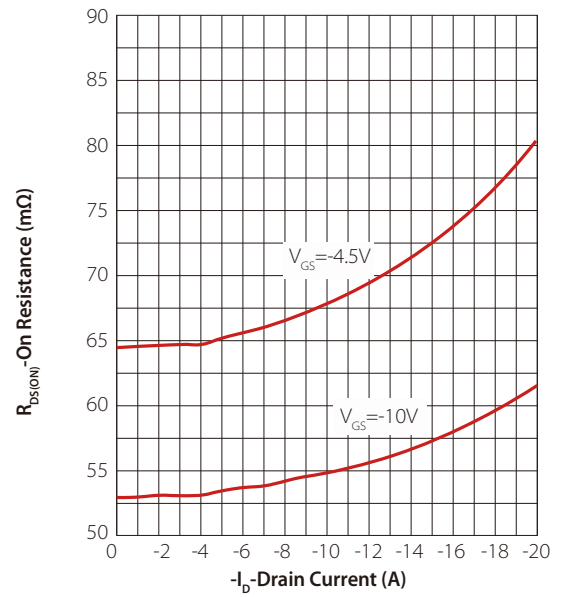


Figure 19: Transfer Characteristics

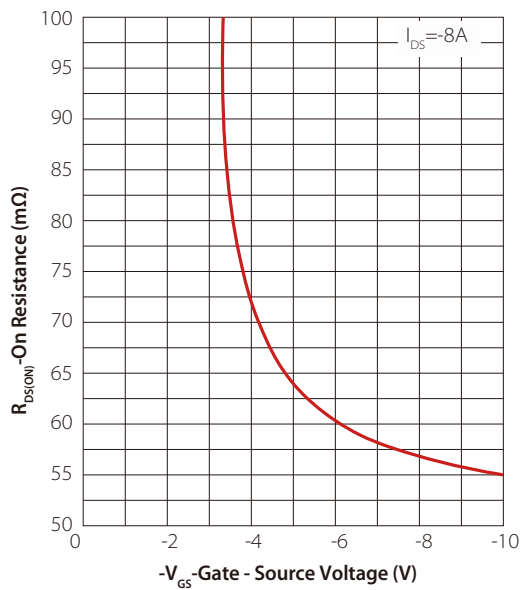


Figure 20: Normalized Threshold Voltage

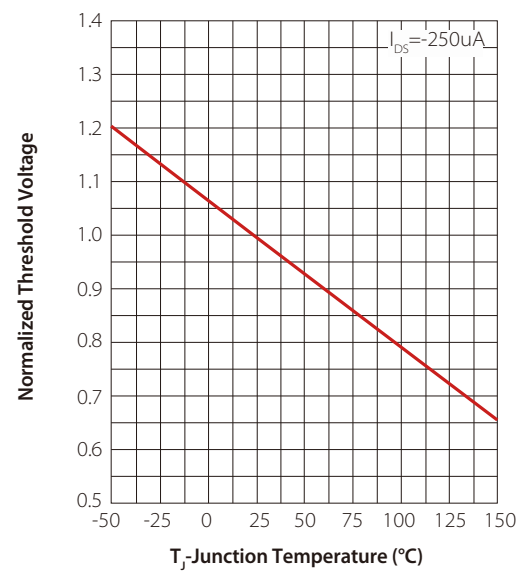
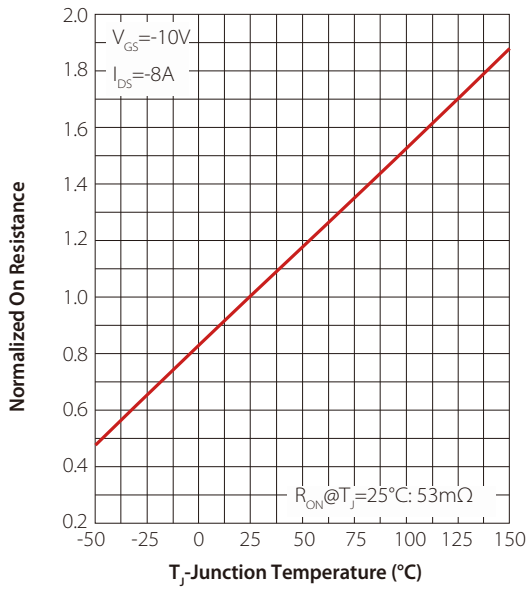
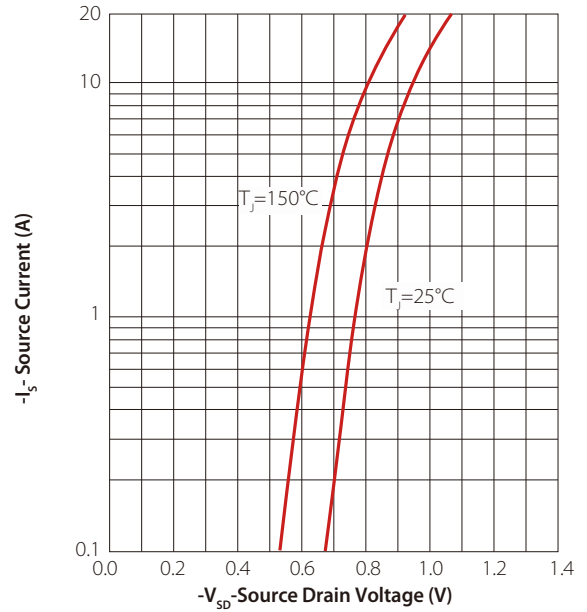
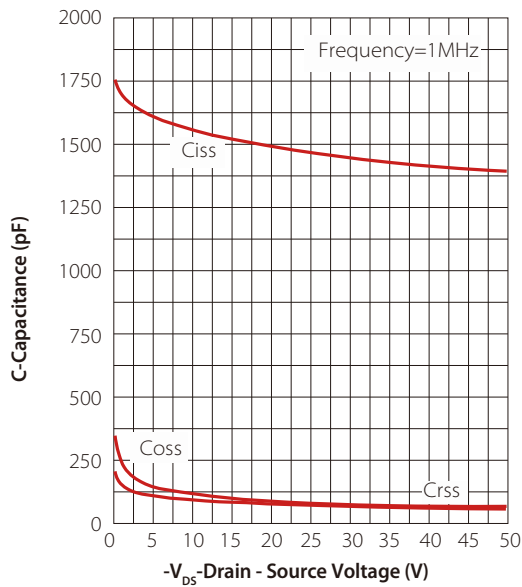
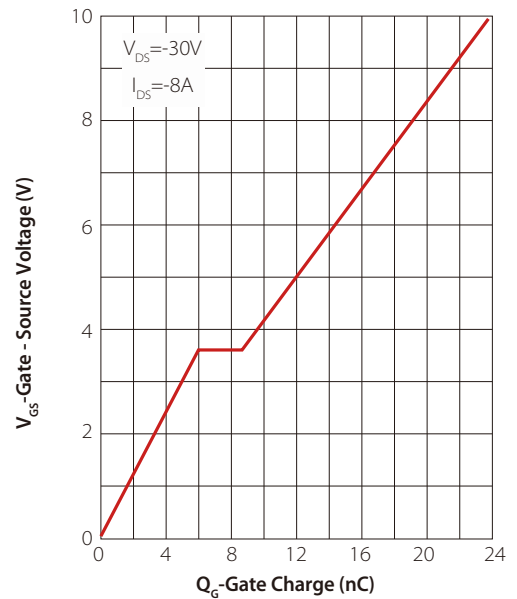
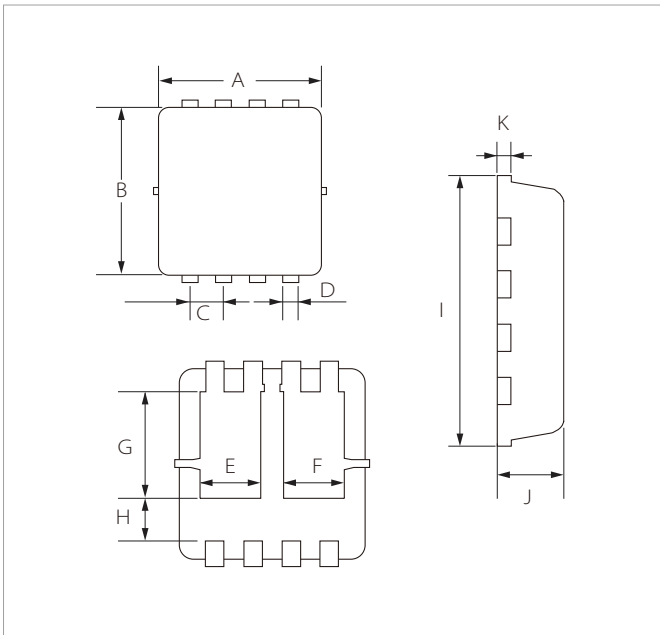


Figure 21: Normalized On Resistance

Figure 22: Diode Forward Current

Figure 23: Capacitance

Figure 24: Gate Charge


PDFN3.3x3.3-8L PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.05	3.25	0.120	0.128
B	3.15	3.55	0.124	0.140
C	0.65		0.026	
D	0.32		0.013	
E	0.835	1.235	0.033	0.049
F	0.835	1.235	0.033	0.049
G	1.53	1.93	0.060	0.076
H	0.49	0.89	0.020	0.035
I	3.10	3.50	0.122	0.138
J	0.675	0.875	0.027	0.034
K	0.152		0.006	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SNPMN66Y06QY	PDFN3.3x3.3-8L	5000PCS	13"

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